

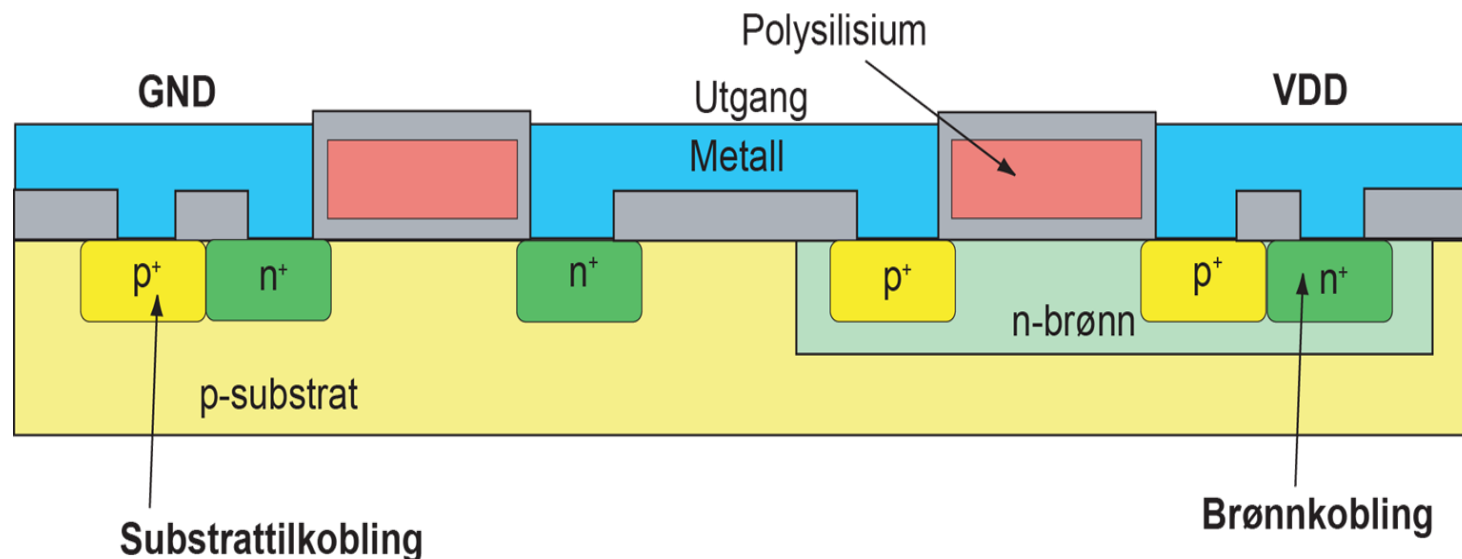


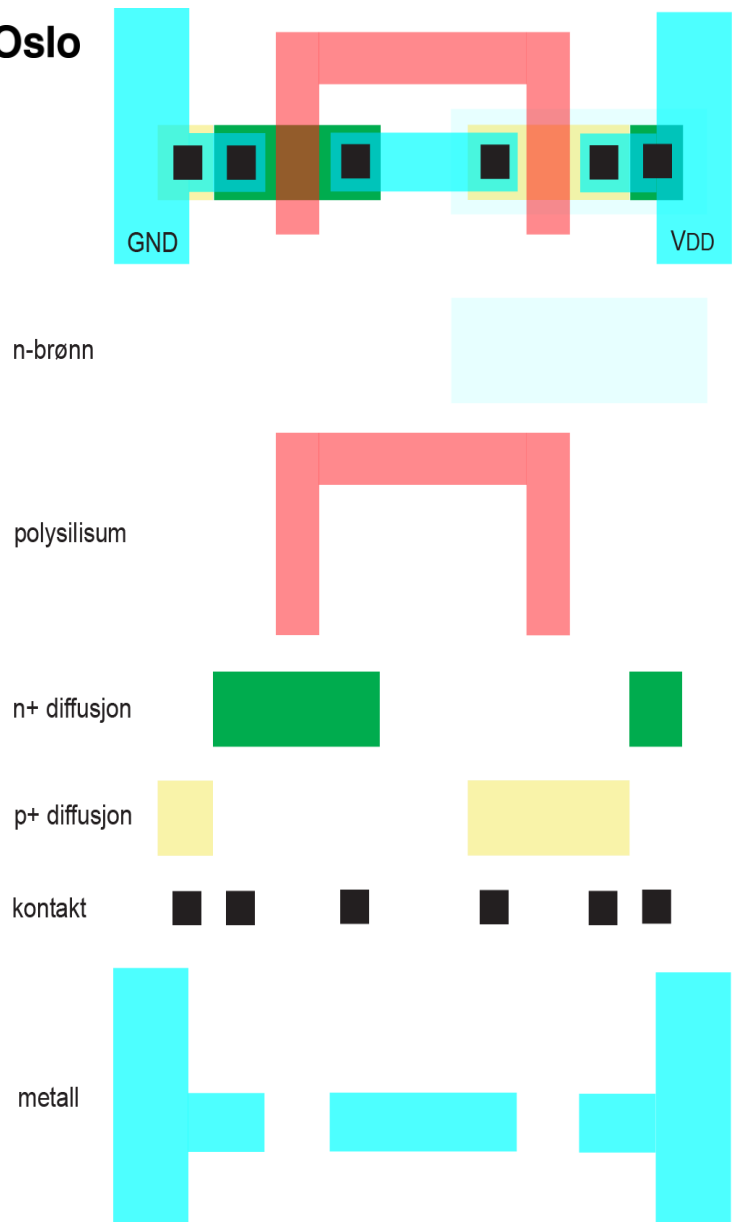
UiO : Universitetet i Oslo

# INF3400 Del 7 Teori CMOS fabrikasjonsprosess og utleggsregler



# Introduksjon til CMOS fabrikasjonsprosess







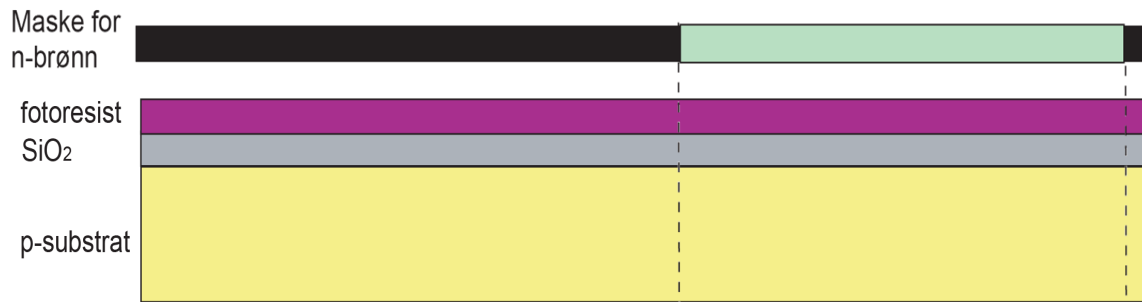
(a)



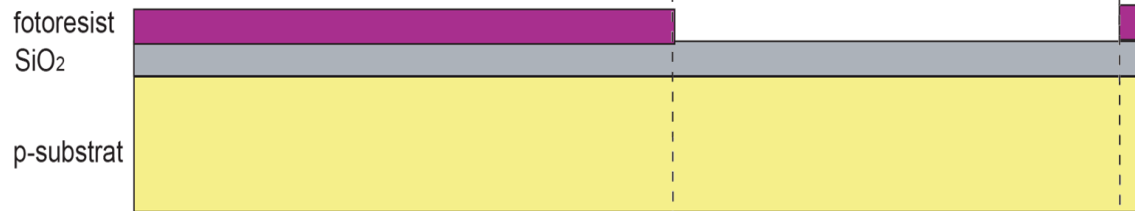
(b)



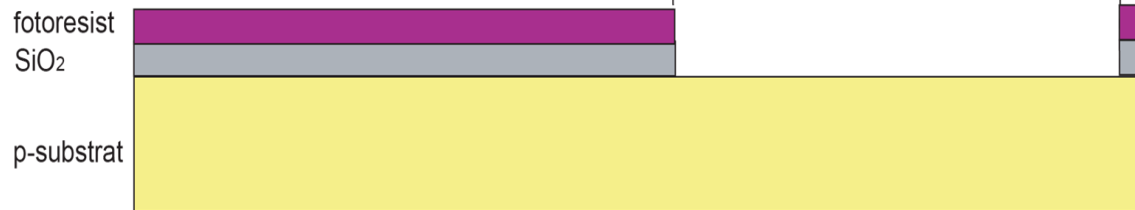
(c)



(c)



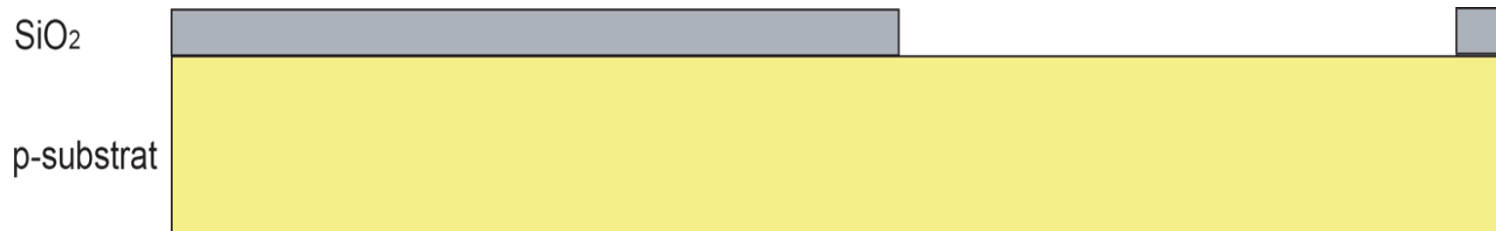
(d)



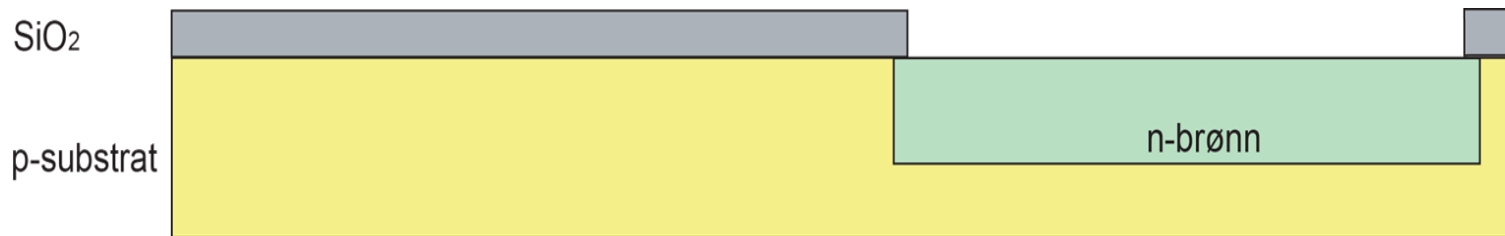
(e)



(f)



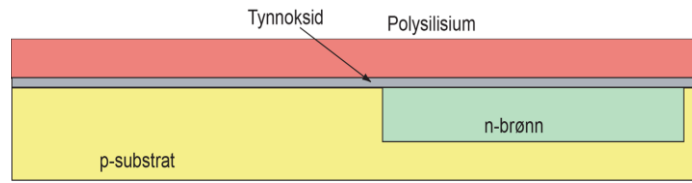
(f)



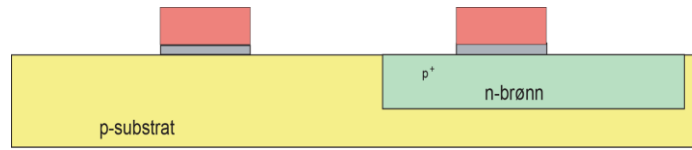
(g)



(h)



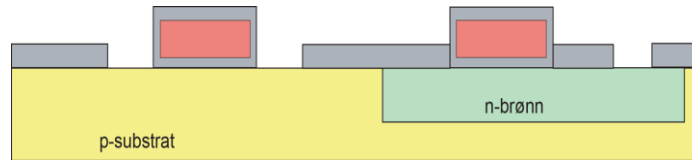
(a)



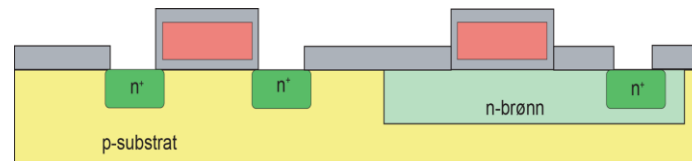
(b)



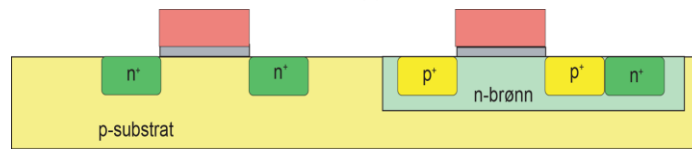
(c)



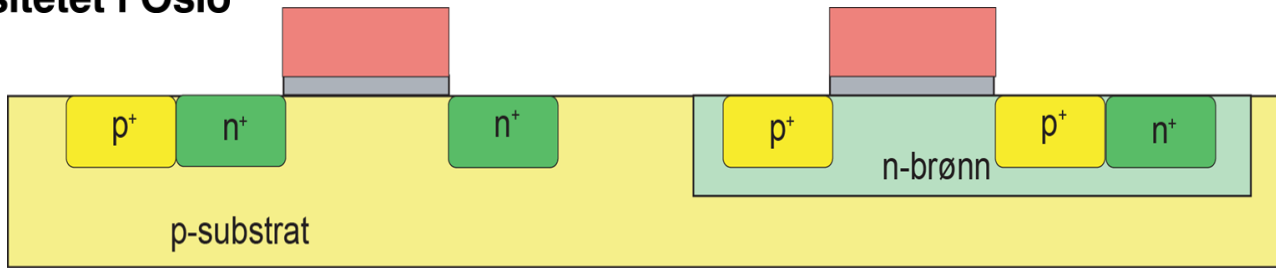
(d)



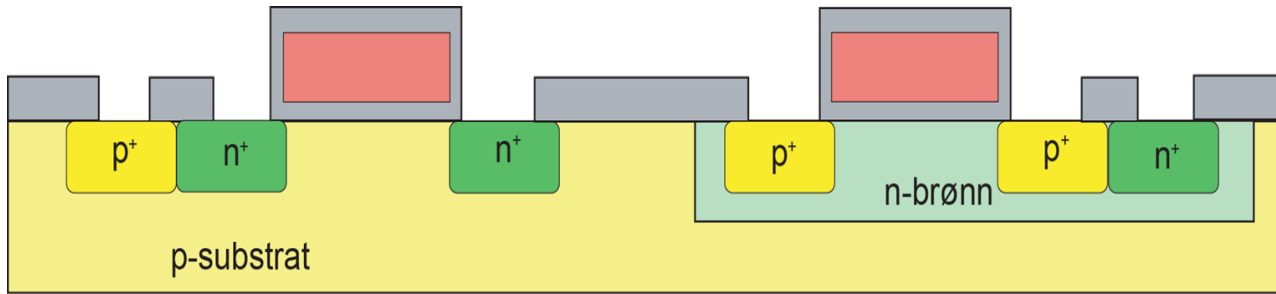
(e)



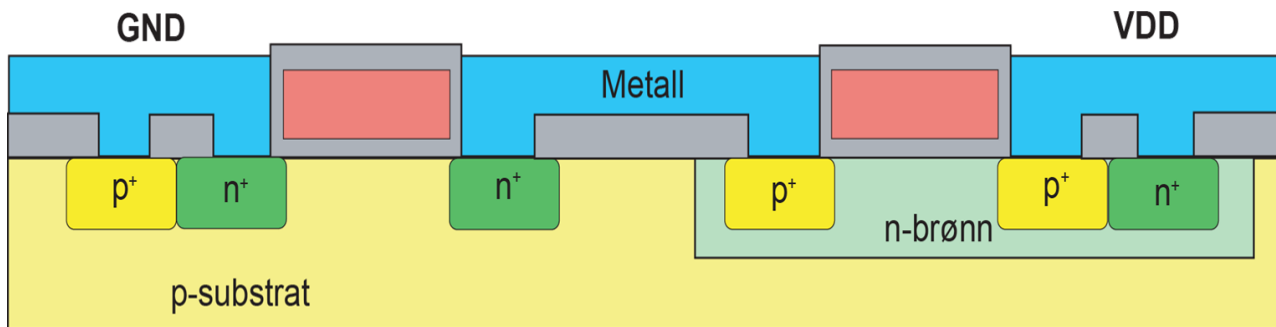
(f)



(a)



(b)



(c)



# Integrerte kretser

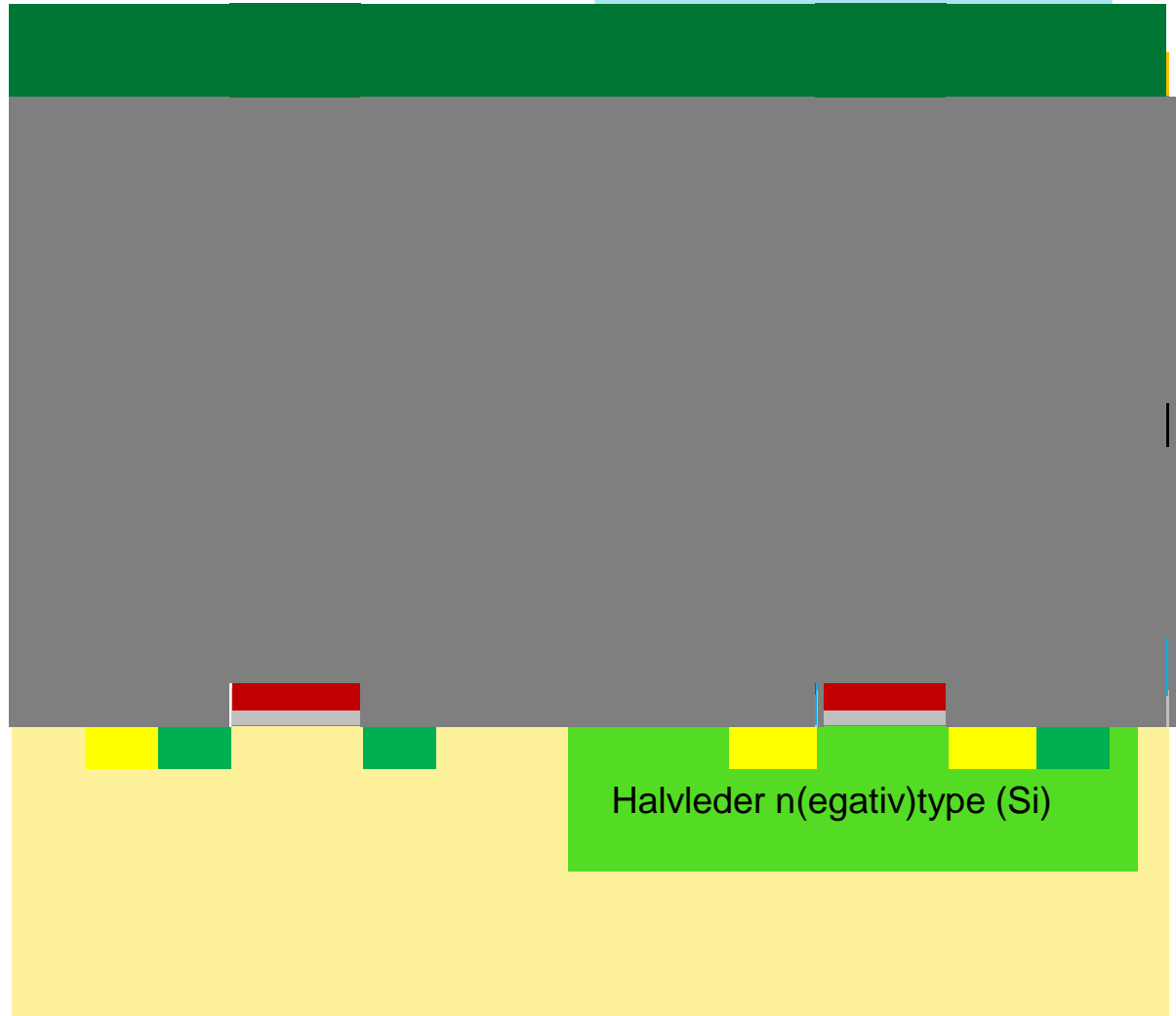
Blått lys (UV)

Maske

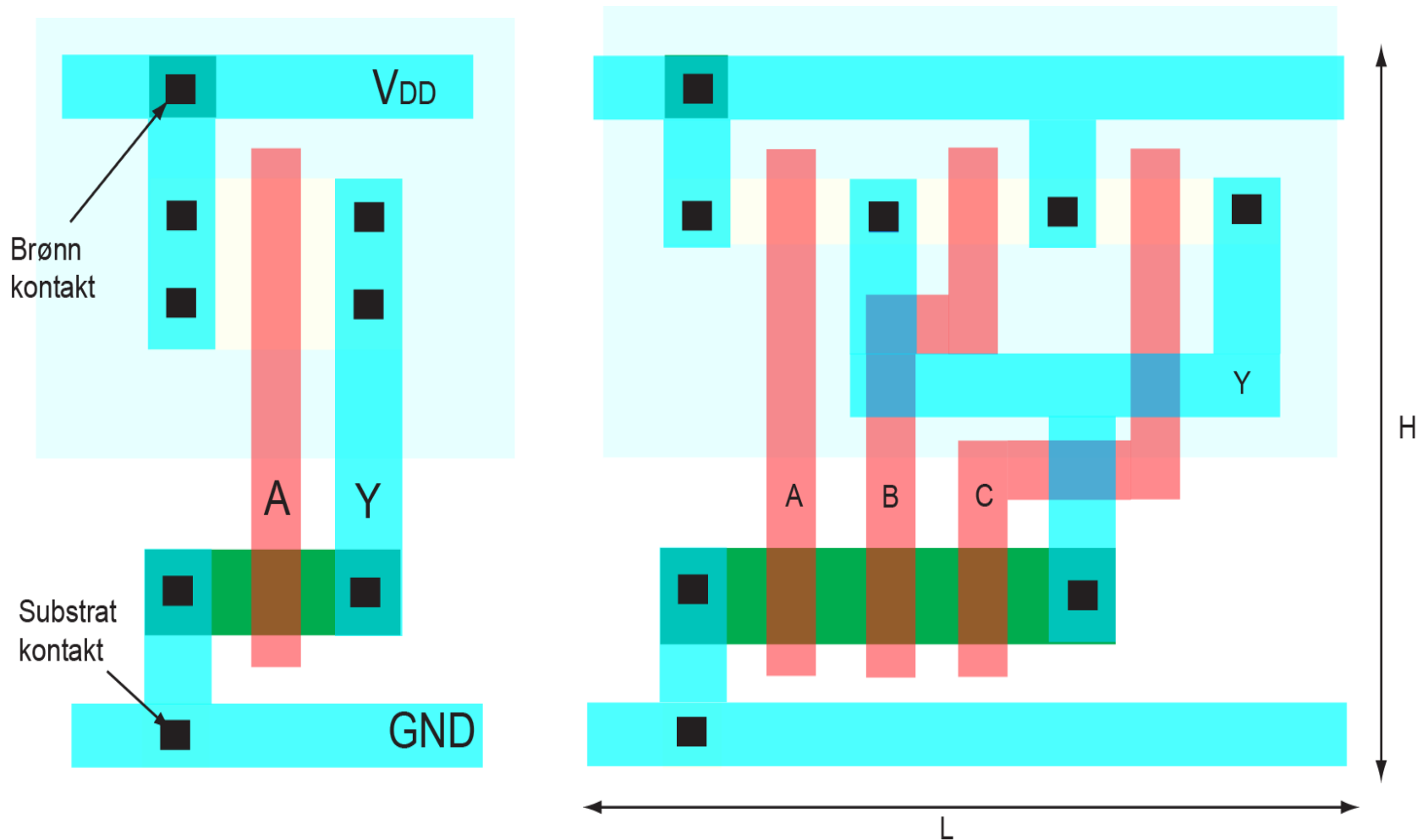
Dielectric ( $SiO_2$ )  
Glassmaske

Polysilicon (halvleder)  
Isolator ( $SiO_2$ )

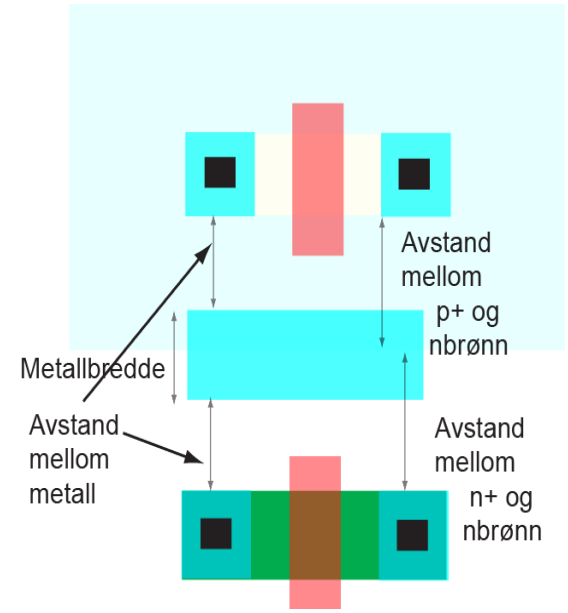
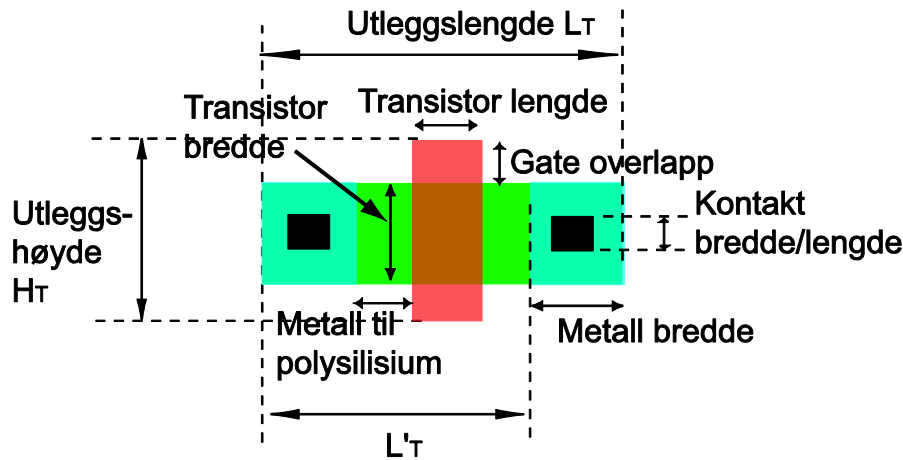
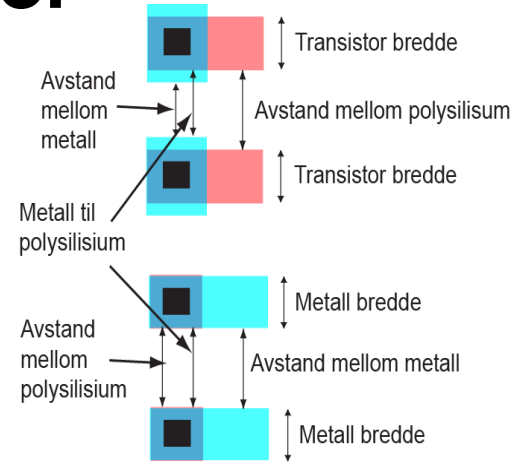
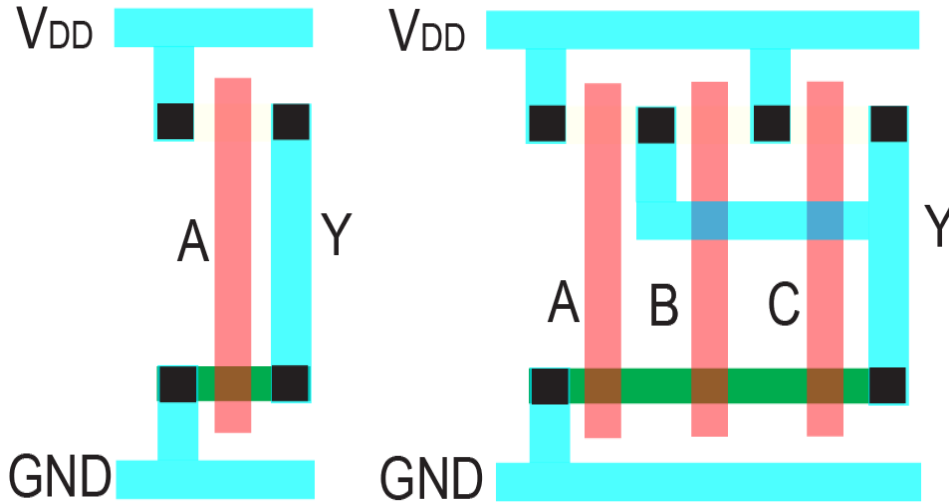
Halvleder n(egativ)type (Si)  
Halvleder p(ositiv)type (Si)

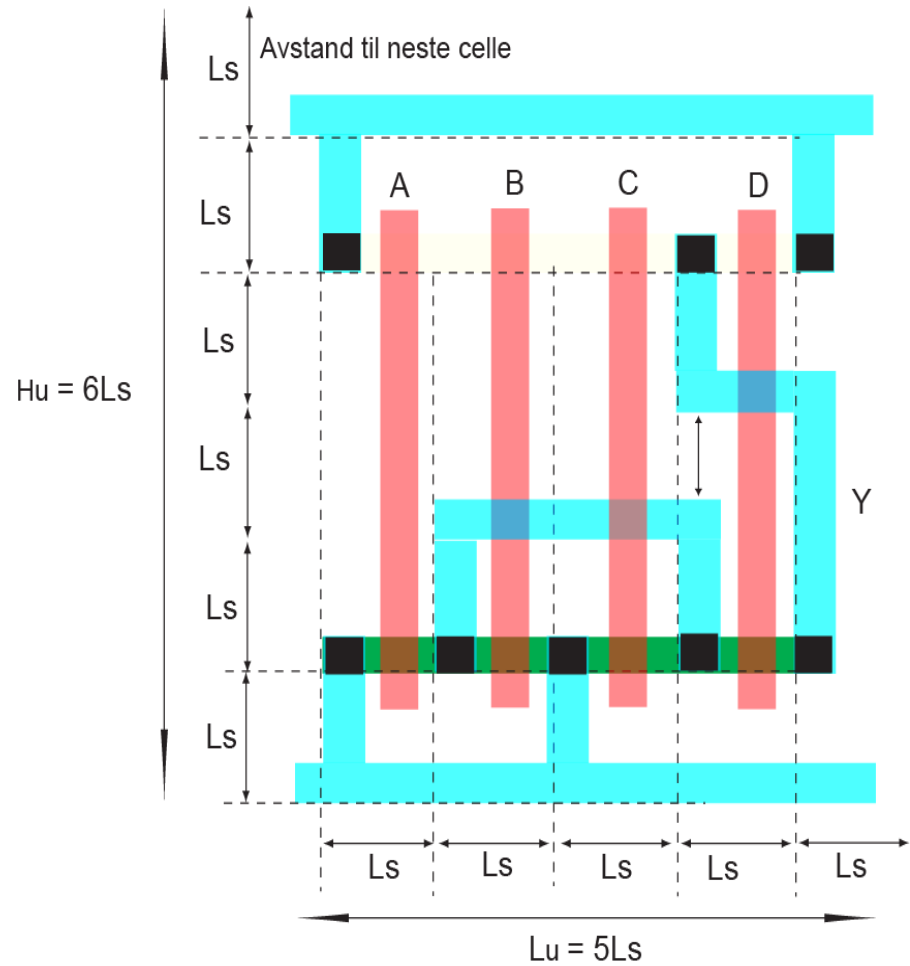
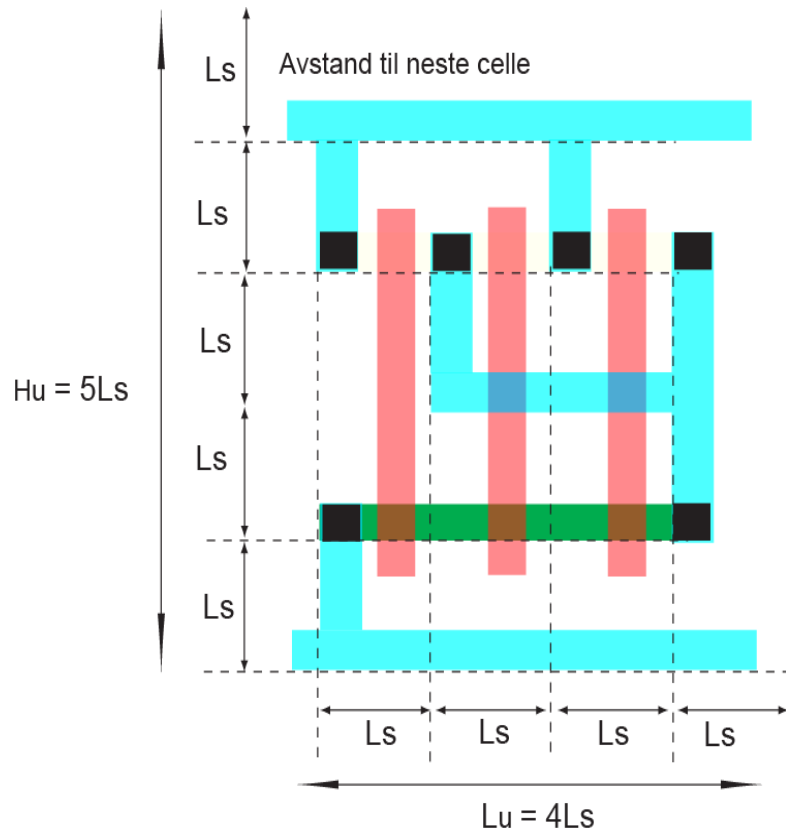


# Utlegg av port

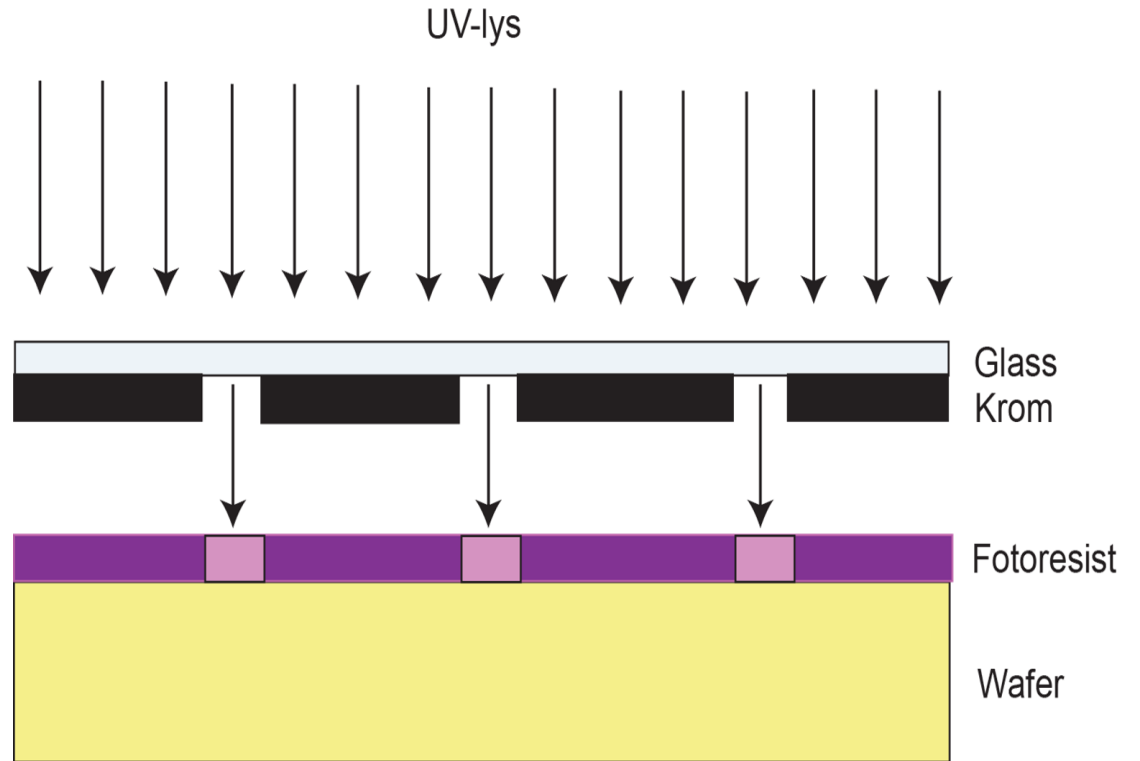


# Stick diagrammer

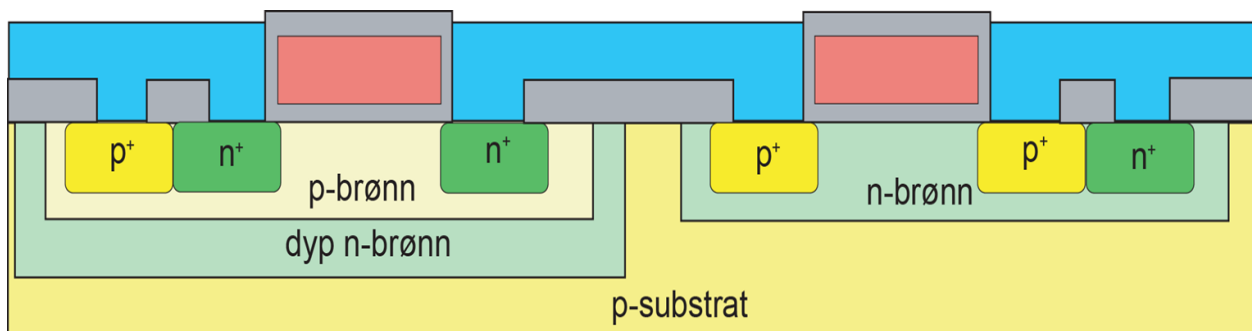




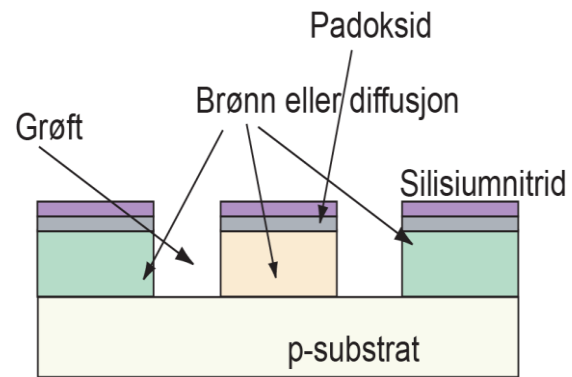
# Fotolitografi



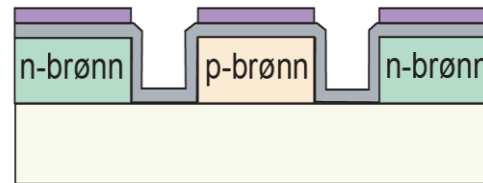
# Fremstilling av brønn og kanal



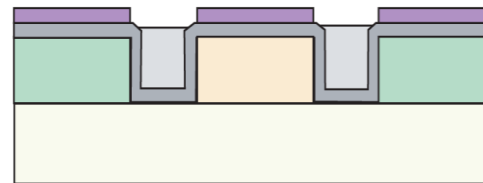
# Isolering



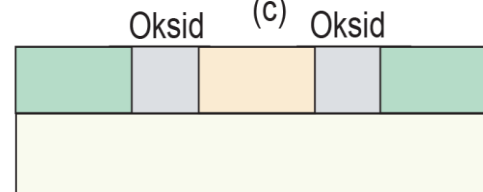
(a)



(b)

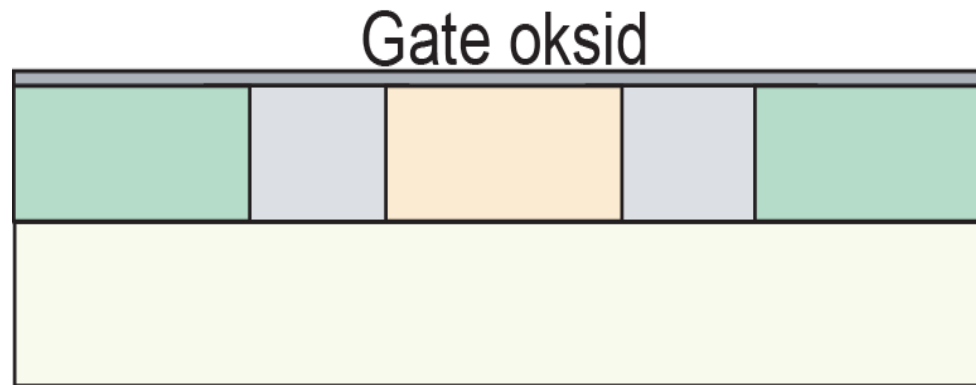


(c)



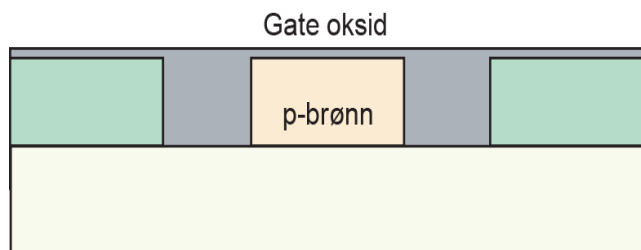
(d)

# Gate oksid

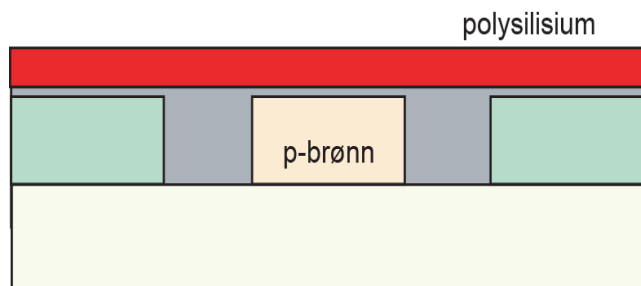




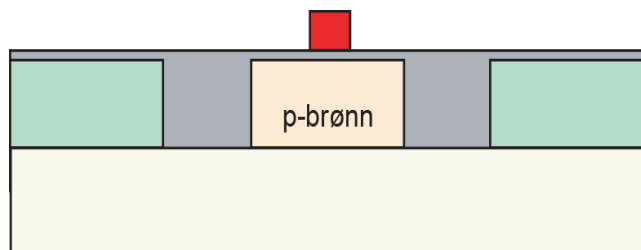
# Fremstilling av source og drain



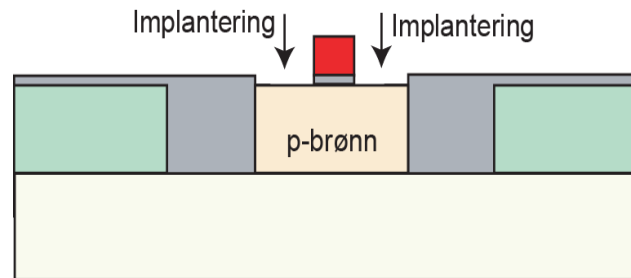
(a)



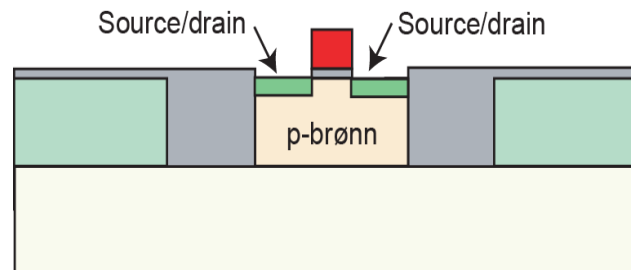
(b)



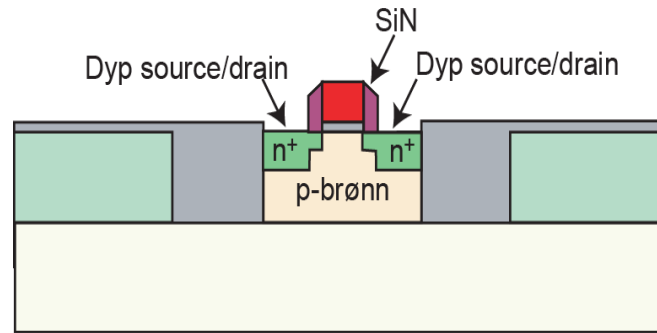
(c)



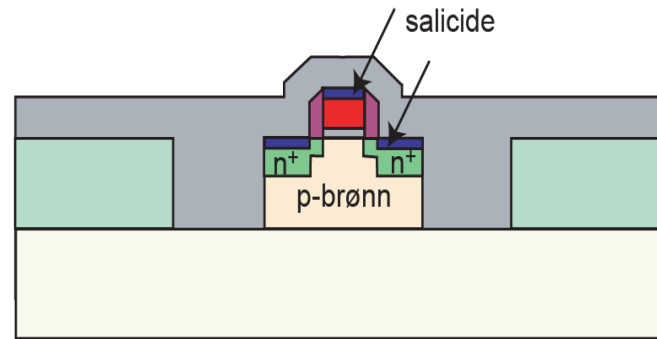
(d)



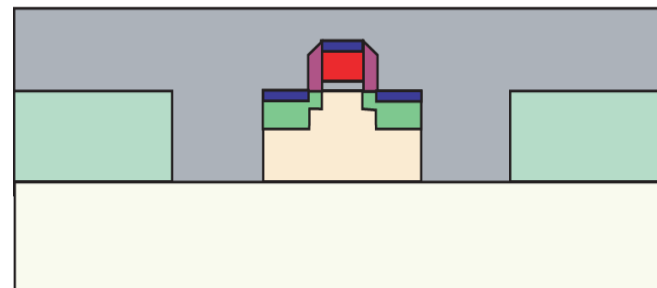
(e)



(a)

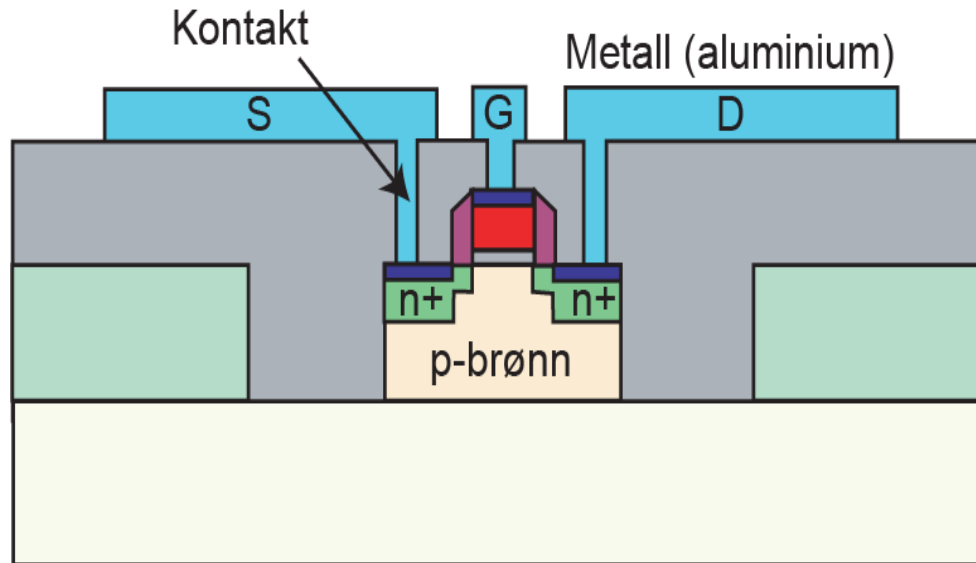


(b)



(c)

# Kontakter



# Metall

